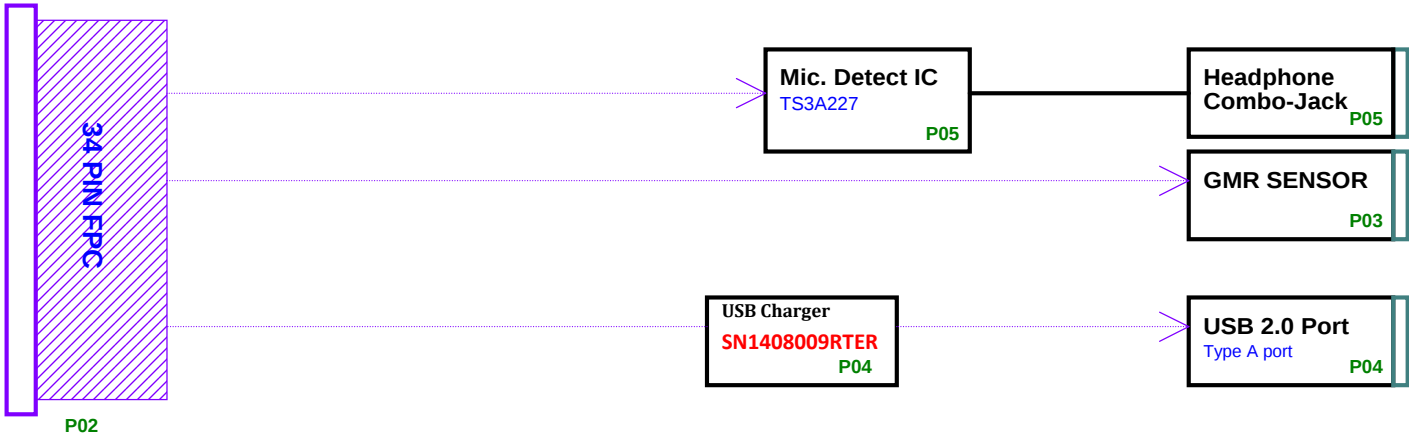


Model	REV	CHANGE LIST	MODEL	
			FROM	To
ZHR/ZHRA	1A	01/02 A01 Changed HSR to EM-1791 for Yoga type (Page 3) A02 Changed Yoga button to slide type(Page 3) A03 Added ESD protector for Dongle issue (Page 4) A04 Level shifter of AJACK_MICPRES_L_227 is moved to MB (Page 5) A05 made connections of I2C_DAT/CLK/INT to MB (Page 5)		
		01/07 A06 corrected ORCAD library of MR1(Page 3)		
		01/08 A07 changed back push button type(Page 3)		
		01/15 A08 Swapped USBP/N on CN3 for layout(Page 3) A09 Added Holes (Page 3) A10 Added option hall sensor called GMR, stuffing GMR(MR2) for yoga SKU(ZHRA), stuffing hall sensor (MR1) for clamshell mode(ZHR) (Page3) A11 changed C25 from 100uF to 220uF(Page23)		
		01/18 A12 Corrected QPN of GMR (Page3)		
		01/19 A13 changed the connector from 30 pin to 34 pin, and added back connection for USB charger(Page 3) A14 updated footprint of GMR (Page 3) A15 added back USB charger(Page 4)		
		01/20 A16 Added Holes(Page3) A17 Changed QPN of USB charger IC (Page 4) A18 swapped pin of L7 for layout(Page 4) A19 changed QPN of C17 (Page 5) A20 changed footprint of Audio jack(Page 5)		
		01/21 A21 corrected SW1 pin(Page3)		
		01/23 A22 Changed QPN of C26,C27 (Page 4)		
	3A	03/04 B01 changed the pullup on LID_OPEN_OUT1_R_L/LID_OPEN_OUT2_R_L to 100K(Page 3)		
		03/05 B02 for DVT build, changed power side button to DIP type (Page 3)		
		03/09 B03 unstuffed USB charger related componenets (Page 4) B04 Added option 0E, default stuff them for non-USB charger (Page 4) B05 added back USB power switch as default stuffed(Page 4)		
		03/10 B06 Changed Hoile1 footprint and added hole4		
		03/12 B07 Changed C27 to 1uF(Page 4) B08 Added Holes (Page 3) B09 Changed back(unstffed R992/R994/R993/R995,U7,C576to USB charger support (Page4)		
	3B	04/20 C01 adjusted pin mapping of audio signals for adding one more GND, made ADOGND_R option on the pin of PP3300_DSW ,default on pin19 is power pin(Page 3) C02 stuffed RV1/RV2 as ESD diode for protecting USB data line(Page 4) C03 added option on USB_CTL_PWR for one more AGND added if recording noise isn't fixed(Page 4)		
		04/27 C04 changed QPN of MIC SW(Page 5)		
		05/06 C05 NC pin35 of Daughter board CONN(Page 3) C06 changed Hall sensor from EM1791 to General hall sensor for ZHR(Page 3)		
	3C	07/06 D01 Added option resistors on LID_OPEN_OUT2_L_CONN for MIC detection issue, R69 is unstuffed(Page 3) D02 unstuffing R991,C575,R307 due to no use on LID_OPEN_OUT2 in convertible device(Page 3) D03 Added option nets on power of 227, stuffing R140 as default(Page 4)		
		07/09 D04 Changed power button for reliable test (Page 3) D05 Changed Footprint of removing mylar for factory side requestPage 3)		
		07/16 D06 Added PAD1-4 as ESD protection(Page 4)		

VER : 1A

BOM P/N	Description
*	Origins IO Board

Block Diagram
(Audio Headset Switch + Phone Jack +
Hall Sensor + USB CONNECTOR)

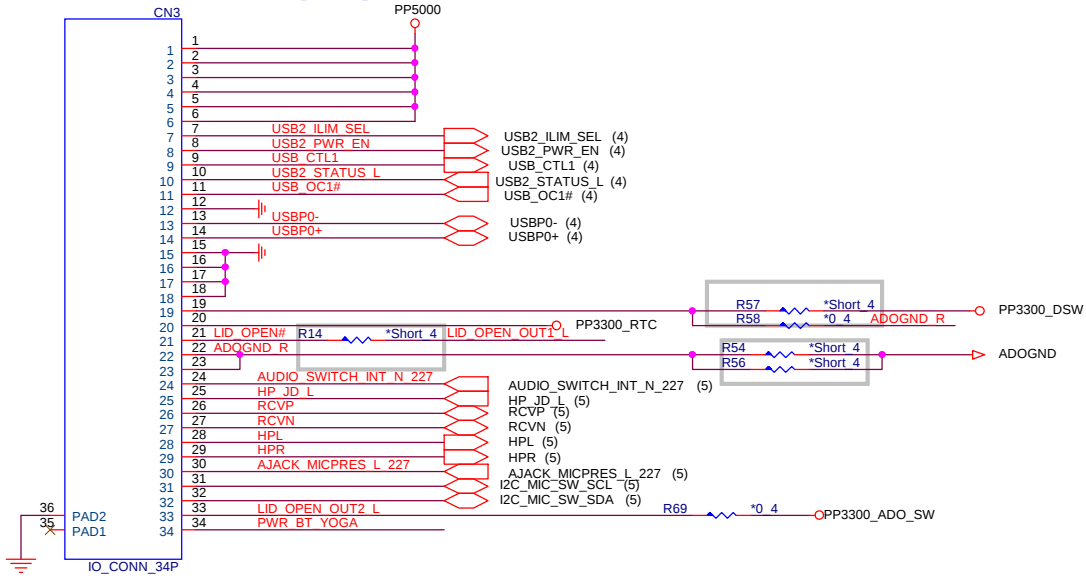


Schematic Marks

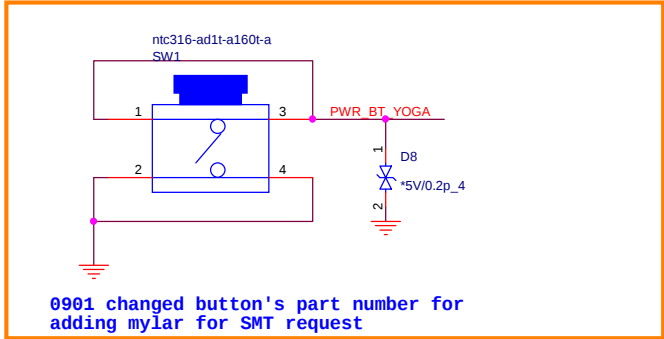
Reference	Description
*	do not stuff
/F	1% esistance

USB2.0: 500mA x1
Charger (DCP): 2A x1
Hall Sensor 3.3V x1

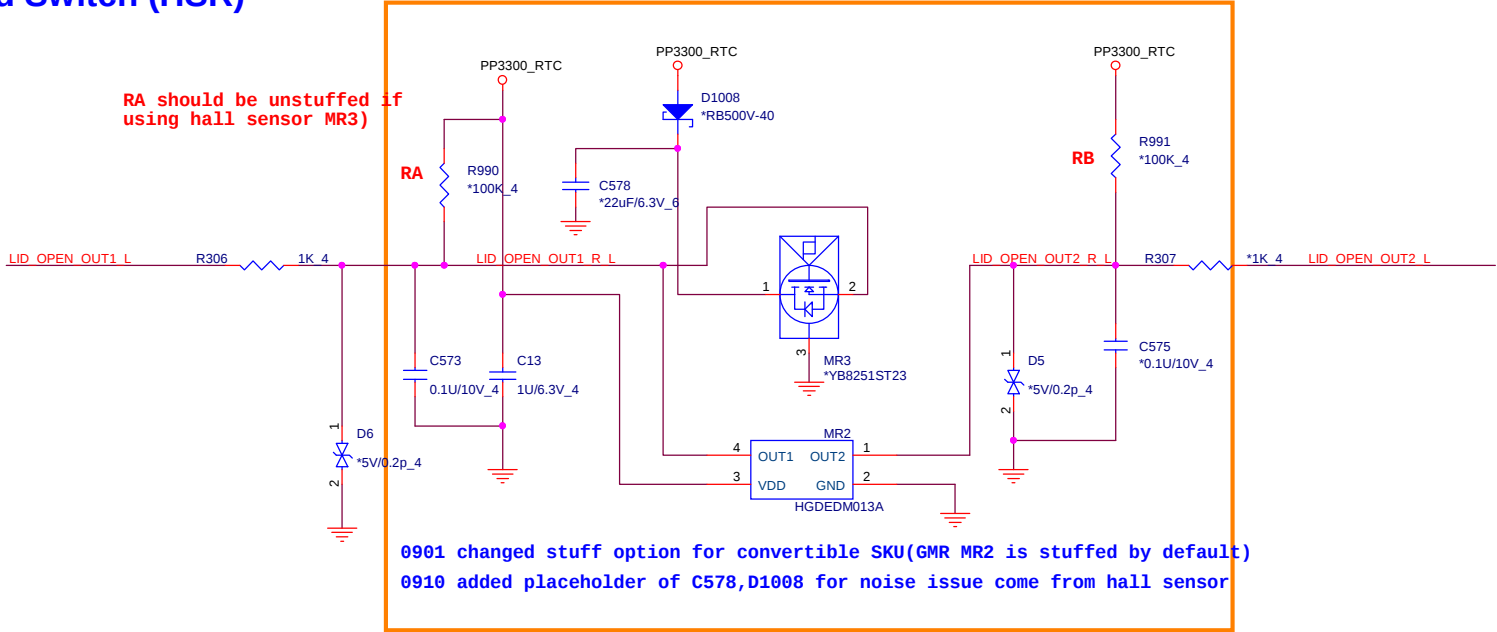
IO Board Connector(UIF)



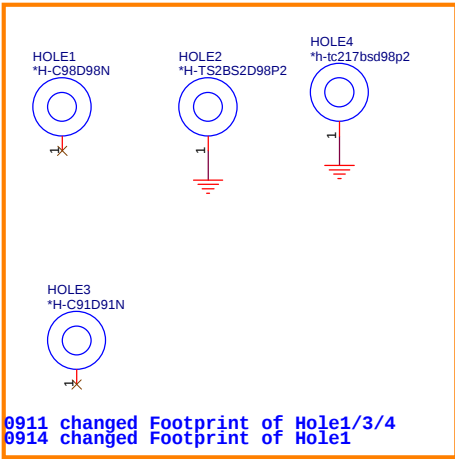
Yoga push button(UIF)



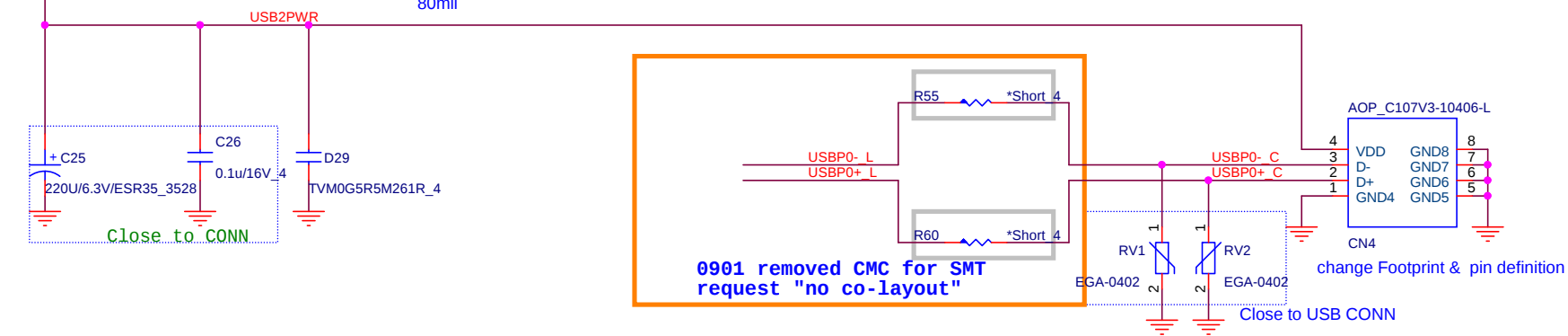
Lid Switch (HSR)



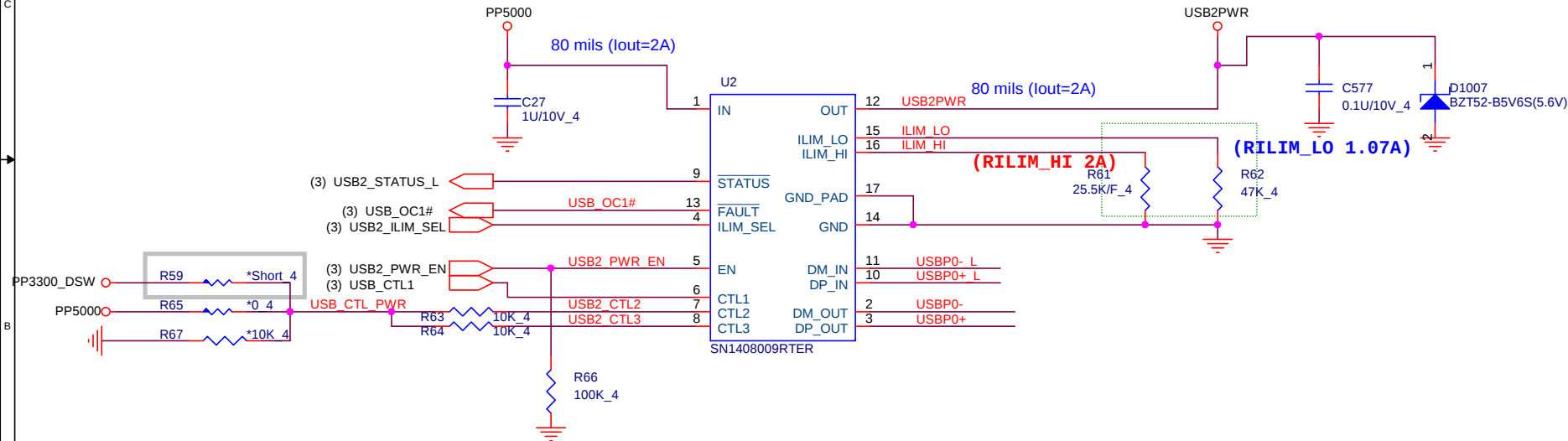
Hole(OTH)



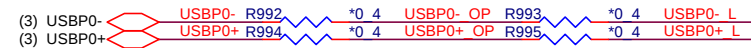
USB 2.0(UB2)



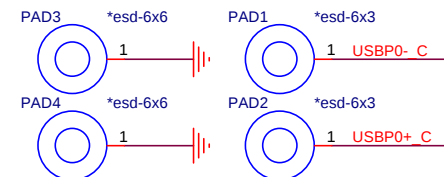
USB Charger(UB2)



USB Colay BOM option



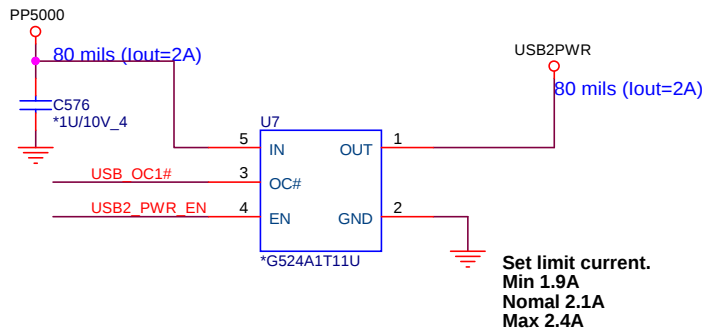
USB2 PCB-ESD protection



Quanta Computer Inc.

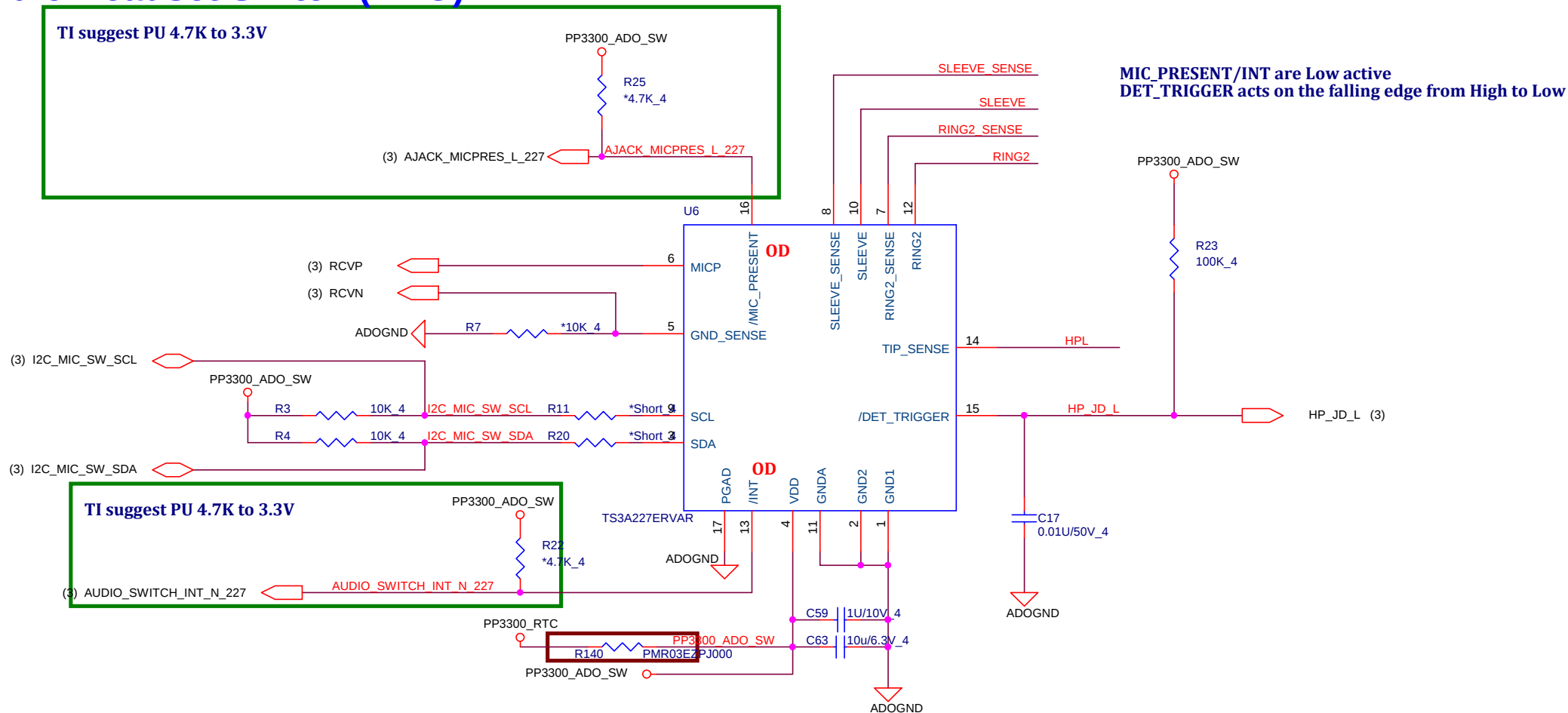
PROJECT : ZHR

Size	Document Number	Rev
	USB 2.0	1A
Date:	Monday, September 14, 2015	Sheet 4 of 5



Audio Headset Switch (ADO)

TI suggest PU 4.7K to 3.3V



Combo Jack (ADO)

